



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	1.00	\approx	1.50	2
A ₁	0.25	0.30	0.40	
A ₂	0.75	0.90	1.10	
$\frac{D}{E}$	15.00 BSC			
$\frac{D_1}{E_1}$	13.60 BSC			
$\frac{e}{e}$	0.80 BSC			
ϕb	0.40	0.45	0.50	
bbb	\approx	\approx	0.20	
ddd	\approx	\approx	0.20	
eee	\approx	\approx	0.15	
fff	\approx	\approx	0.08	
M	18			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. THERE SHALL BE A MINIMUM CLEARANCE OF 0.25mm BETWEEN THE EDGE OF THE SOLDER BALL AND THE BODY EDGE
5. CONFORMS TO JEDEC MO-275-KKAB-1

PK381_01_111209

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.
11/23/09	1.1	Changed the orientation of the A1 ball pad corner indicator.

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